8-Bit Serial or Parallel-Input/ Serial-Output Shift Register

IN74HC165A

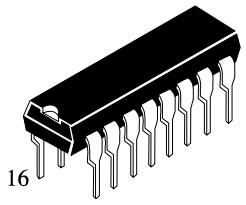
High-Performance Silicon-Gate CMOS

The IN74HC165A is identical in pinout to the LS/ALS165. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LS/ALSTTL outputs.

This device is an 8-bit shift register with complementary outputs from the last stage. Data may be loaded into the register either in parallel or in serial form. When the Serial Shift/ Parallel Load input is low, the data is loaded asynchronously in parallel. When the Serial Shift/Parallel Load input is high, the data is loaded serially on the rising edge of either Clock or Clock Inhibit (see the Function Table).

The 2-input NOR clock may be used either by combining two independent clock sources or by designating one of the clock inputs to act as a clock inhibit.

- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μA
- High Noise Immunity Characteristic of CMOS Devices

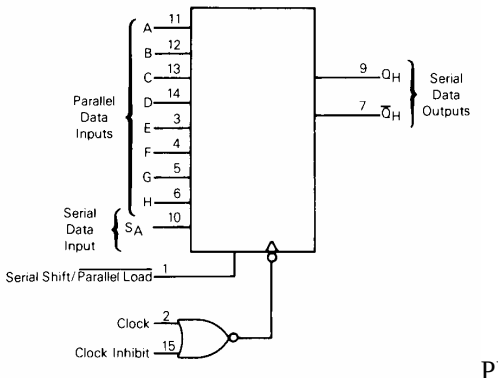


N SUFFIX
PLASTIC

D SUFFIX
SOIC

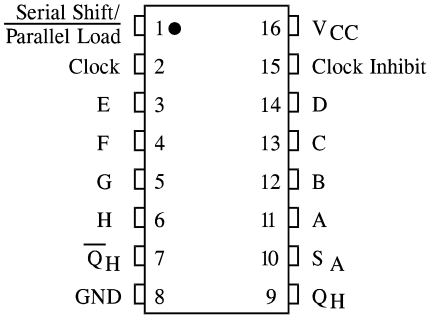
ORDERING INFORMATION
IN74HC165AN Plastic
IN74HC165AD SOIC
T_A = -55° to 125° C for all packages

LOGIC DIAGRAM



PIN 16=V_{CC}
PIN 8 = GND

PIN ASSIGNMENT



FUNCTION TABLE

Inputs					Internal Stages		Output	Operation
Serial Shift/ Parallel Load	Clock	Clock Inhibit	S_A	A-H	Q_A	Q_B-Q_G	Q_H	
L	H	X	X	a...h	a	b-g	h	Asynchronous Parallel Load
H	⌐	L	L	X	L	Q_{An}-Q_{Fn}	Q_{Gn}	Serial Shift via Clock
H	⌐	L	H	X	H	Q_{An}-Q_{Fn}	Q_{Gn}	
H	L	⌐	L	X	L	Q_{An}-Q_{Fn}	Q_{Gn}	Serial Shift via Clock
H	L	⌐	H	X	H	Q_{An}-Q_{Fn}	Q_{Gn}	Inhibit
H	X	H	X	X	no change			Inhibited Clock
H	H	X	X	X				
H	L	L	X	X	no change			No Clock

X = Don't Care
Q_{An}-Q_{Fn} = Data shifted from the preceding stage

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	-1.5 to V_{CC} +1.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	-0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Current, per Pin	±25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	±50	mA
P_D	Power Dissipation in Still Air, Plastic DIP+ SOIC Package+	750 500	mW
Tstg	Storage Temperature	-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

*Maximum Ratings are those values beyond which damage to the device may occur.
Functional operation should be restricted to the Recommended Operating Conditions.
+Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C
SOIC Package: : - 7 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)		2.0	6.0	V
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Referenced to GND)		0	V_{CC}	V
T_A	Operating Temperature, All Package Types		-55	+125	°C
t_r, t_f	Input Rise and Fall Time (Figure 1)	V_{CC} =2.0 V V_{CC} =4.5 V V_{CC} =6.0 V	0 0 0	1000 500 400	ns

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{IN} and V_{OUT} should be constrained to the range GND≤(V_{IN} or V_{OUT})≤V_{CC}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V_{CC} V	Guaranteed Limit			Unit
				25 °C to -55°C	≤85 °C	≤125 °C	
V_{IH}	Minimum High-Level Input Voltage	V_{OUT}=0.1 V or V_{CC}-0.1 V $\|I_{OUT}\| \le 20$ μA	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V_{IL}	Maximum Low - Level Input Voltage	V_{OUT}=0.1 V or V_{CC}-0.1 V $\|I_{OUT}\| \le 20$ μA	2.0 4.5 6.0	0.3 0.9 1.2	0.3 0.9 1.2	0.3 0.9 1.2	V
V_{OH}	Minimum High-Level Output Voltage	V_{IN}=V_{IH} or V_{IL} $\|I_{OUT}\| \le 20$ μA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		V_{IN}=V_{IH} or V_{IL} $\|I_{OUT}\| \le 4.0$ mA $\|I_{OUT}\| \le 5.2$ mA	 4.5 6.0	 3.98 5.48	 3.84 5.34	 3.7 5.2	
V_{OL}	Maximum Low-Level Output Voltage	V_{IN}= V_{IL} or V_{IH} $\|I_{OUT}\| \le 20$ μA	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		V_{IN}= V_{IL} or V_{IH} $\|I_{OUT}\| \le 4.0$ mA $\|I_{OUT}\| \le 5.2$ mA	 4.5 6.0	 0.26 0.26	 0.33 0.33	 0.4 0.4	
I_{IN}	Maximum Input Leakage Current	V_{IN}=V_{CC} or GND	6.0	±0.1	±1.0	±1.0	μA
I_{CC}	Maximum Quiescent Supply Current (per Package)	V_{IN}=V_{CC} or GND I_{OUT}=0μA	6.0	8.0	80	160	μA

AC ELECTRICAL CHARACTERISTICS (C_L=50pF,Input t_r=t_f=6.0 ns)

Symbol	Parameter	V_{CC} V	Guaranteed Limit			Unit
			25 °C to -55°C	≤85°C	≤125°C	
f_{max}	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 8)	2.0 4.5 6.0	6.0 30 35	4.8 24 28	4.0 20 24	MHz
t_{PLH}, t_{PHL}	Maximum Propagation Delay, Clock (or Clock Inhibit) to Q_H or $\overline{Q_H}$ (Figures 1 and 8)	2.0 4.5 6.0	150 30 26	190 38 33	225 45 38	ns
t_{PLH}, t_{PHL}	Maximum Propagation Delay , SerialShift./.$\overline{\text{Parallel Load}}$ to Q_H or $\overline{Q_H}$ (Figures 2 and 8)	2.0 4.5 6.0	175 35 30	220 44 37	265 53 45	ns
t_{PLH}, t_{PHL}	Maximum Propagation Delay, Input H to Q_H or $\overline{Q_H}$ (Figures 3 and 8)	2.0 4.5 6.0	150 30 26	190 38 33	225 45 38	ns
t_{TLH}, t_{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 8)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C_{IN}	Maximum Input Capacitance	-	10	10	10	pF

C_{PD}	Power Dissipation Capacitance (Per Package) Used to determine the no-load dynamic power consumption: $P_D=C_{PD}V_{CC}^2f+I_{CC}V_{CC}$	Typical @25°C,V_{CC}=5.0 V 85	pF

TIMING REQUIREMENTS (C_L=50pF,Input t_r=t_f=6.0 ns)

Symbol	Parameter	V_{CC} V	Guaranteed Limit			Unit
			25 °C to -55°C	≤85°C	≤125°C	
t_{SU}	Minimum Setup Time, Parallel Data Inputs to Serial Shift/Parallel Load (Figure 4)	2.0 4.5 6.0	100 20 17	125 25 21	150 30 26	ns
t_{SU}	Minimum Setup Time, Input S_A to Clock (or Clock Inhibit) (Figure 5)	2.0 4.5 6.0	100 20 17	125 25 21	150 30 26	ns
t_{SU}	Minimum Setup Time, Serial Shift/Parallel Load to Clock (or Clock Inhibit) (Figure 6)	2.0 4.5 6.0	100 20 17	125 25 21	150 30 26	ns
t_{SU}	Minimum Setup Time, Clock to Clock Inhibit (Figure 7)	2.0 4.5 6.0	100 20 17	125 25 21	150 30 26	ns
t_h	Minimum Hold Time, Serial Shift/Parallel Load to Parallel Data Inputs (Figure 4)	2.0 4.5 6.0	5 5 5	5 5 5	5 5 5	ns
t_h	Minimum Hold Time, Clock (or Clock Inhibit) to Input S_A (Figure 5)	2.0 4.5 6.0	5 5 5	5 5 5	5 5 5	ns
t_h	Minimum Hold Time, Clock (or Clock Inhibit) to Serial Shift/Parallel Load (Figure 6)	2.0 4.5 6.0	5 5 5	5 5 5	5 5 5	ns
t_{rec}	Minimum Recovery Time, Clock to Clock Inhibit (Figure 7)	2.0 4.5 6.0	100 20 17	125 25 21	150 30 26	ns
t_w	Minimum Pulse Width, Clock (or Clock Inhibit) (Figure 1)	2.0 4.5 6.0	80 16 14	100 20 17	120 24 20	ns
t_w	Minimum Pulse Width, Serial Shift/Parallel Load (Figure 2)	2.0 4.5 6.0	80 16 14	100 20 17	120 24 20	ns
t_r, t_f	Maximum Input Rise and Fall Times (Figure 1)	2.0 4.5 6.0	1000 500 400	1000 500 400	1000 500 400	ns

SWITCHING WAVEFORMS

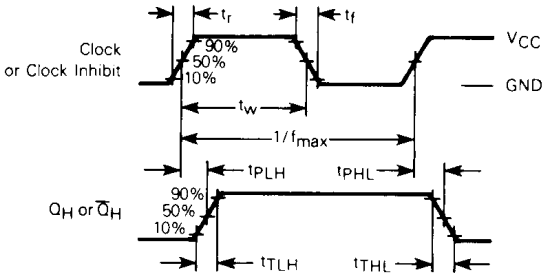


Figure 1. Serial-Shift Mode

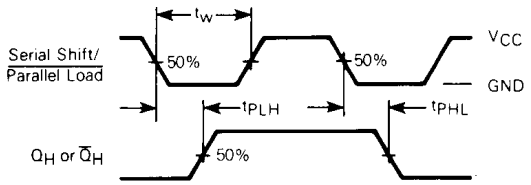


Figure 2. Parallel-Load Mode

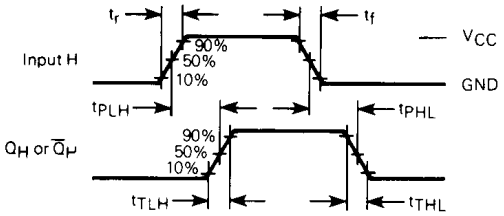


Figure 3. Parallel-Load Mode

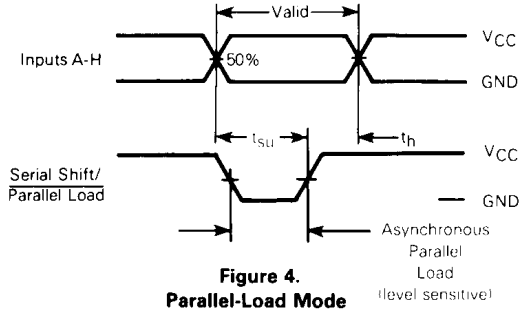


Figure 4.
Parallel-Load Mode

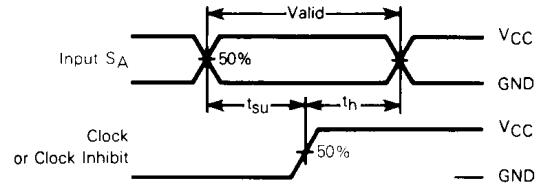


Figure 5. Serial-Shift Mode

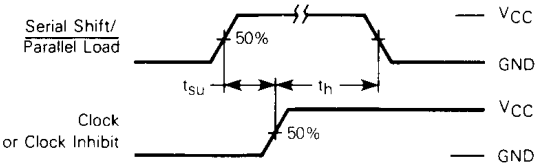


Figure 6. Serial-Shift Mode

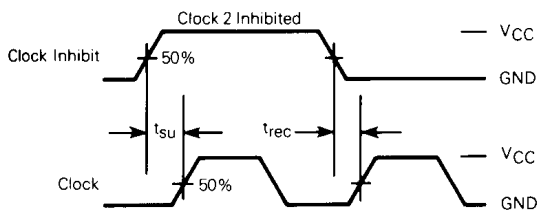


Figure 7. Serial-Shift,
Clock-Inhibit Mode

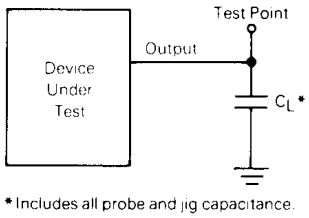
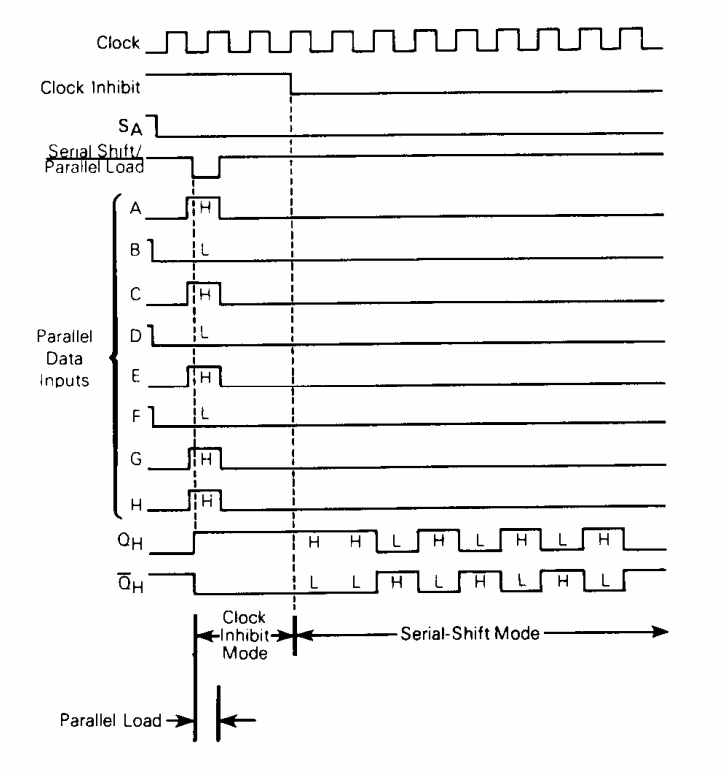
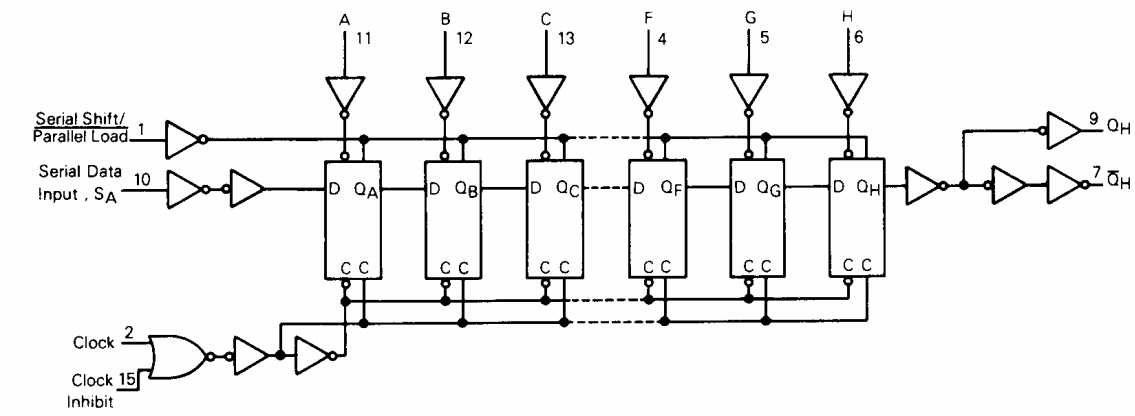


Figure 8. Test Circuit

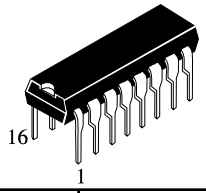
TIMING DIAGRAM

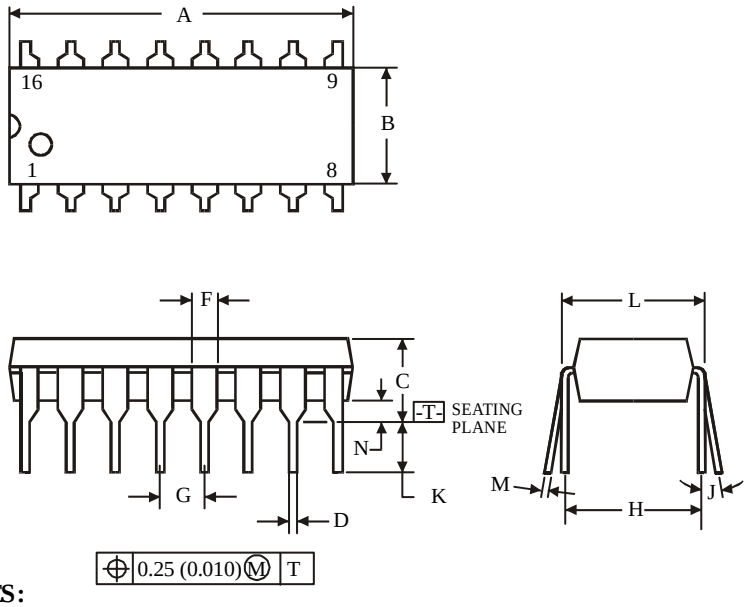


EXPANDED LOGIC DIAGRAM



N SUFFIX PLASTIC DIP
(MS - 001BB)



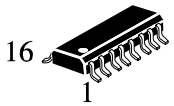


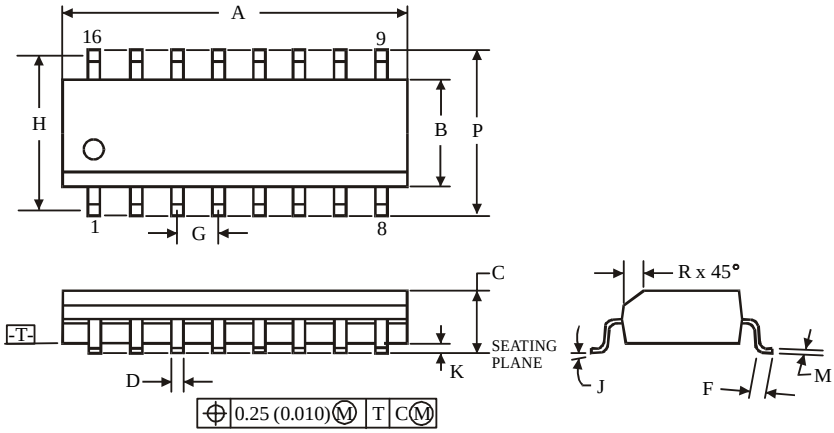
	Dimension, mm	
Symbol	**MIN**	**MAX**
A	18.67	19.69
B	6.1	7.11
C		5.33
D	0.36	0.56
F	1.14	1.78
G	2.54	
H	7.62	
J	0°	10°
K	2.92	3.81
L	7.62	8.26
M	0.2	0.36
N	0.38	

NOTES:

1. Dimensions “A”, “B” do not include mold flash or protrusions.
   Maximum mold flash or protrusions 0.25 mm (0.010) per side.

D SUFFIX SOIC
(MS - 012AC)





	Dimension, mm	
Symbol	**MIN**	**MAX**
A	9.8	10
B	3.8	4
C	1.35	1.75
D	0.33	0.51
F	0.4	1.27
G	1.27	
H	5.72	
J	0°	8°
K	0.1	0.25
M	0.19	0.25
P	5.8	6.2
R	0.25	0.5

NOTES:

1. Dimensions A and B do not include mold flash or protrusion.
2. Maximum mold flash or protrusion 0.15 mm (0.006) per side
   for A; for B – 0.25 mm (0.010) per side.